

Claims

What is claimed is:

1. A chip sorting method, comprising the steps of;
 - 5 (a) having a wafer on the first platform, said wafer at least comprises a chip;
 - (b) lifting up a positioning axis of said first platform to withstand said chip;
 - (c) using a probe of said robotic arm to inspect said chip; and
 - (d) using a second robotic arm to suck said chip, and to place it to the
 - 10 second platform.
2. The method according to claim 1, wherein said second platform at least comprises a specialized bin.
3. The method according to claim 1, wherein said test can include an electricity test for inspecting the said chip.
- 15 4. The method according to claim 2, wherein said step(d) further includes the test following step(c), and it places the chip to said pre-sorting specialized bin.
5. The method according to claim 1, wherein said step(a) further includes pre-cutting said wafer for dividing said chip.
- 20 6. The method according to claim 1, wherein said step(a) further includes said wafer processing the chipping on the blue film after cutting.
7. A chip sorting apparatus, comprising;
 - a first platform providing a place for wafer, and said wafer at least
 - 25 including a chip;
 - a positioning axis setting under the first platform, and having a withstand-end for lift and down;

- a first robotic arm having a probe;
a second robotic arm having a sucking mechanism; and
a second platform providing the place for said chip;
wherein said withstand-end can use lift-down to withstand said chip, It
5 uses said probe to inspect the said chip, and then, it uses said
sucking mechanism to suck the chip, and places it to said second
platform.
8. The apparatus according to claim 7, wherein said second platform at
least includes a specialized bin.
- 10 9. The apparatus according to claim 7, wherein said test can include an
electric test for inspecting said chip.
10. The apparatus according to claim 8, wherein it can rely on the test of
said probe, and place the chip to said pre-sorting specialized bin.
11. The apparatus according to claim 7, wherein said wafer is positioned
15 on said first platform and is pre-cut for dividing said chip.
12. The apparatus according to claim 11, wherein said wafer setting in
the said platform, and said wafer is positioned on the blue film and
processes a chipping after being cut.